It can be seen from the data in Figure 4 that, of the above-mentioned four different electroplating techniques, the constant-voltage pulse plating technique provides the highest electrodeposition uniformity.

The paragraph bridging pages 136 and 137 is amended as follows:

As to the multilayer printed circuit board according to Example 17, solder bumps 6076U, 6076D were disposed at the position a little far from the plated-through holes 6036. On the other hand, as to the multilayer printed circuit board according to Example 22, solder bumps 6O76U, 6076D were disposed immediately over the upper via holes 6160. Therefor, the multilayer printed circuit board according to Example 22 had an advantage that the plated-through hole 6036, lower-layer via hole 6060, upper-layer via hole 6160and solder bumps 6076U, 6076D can be lined up in good registration so that the wiring length can be reduced to increase the transmission speed of signals, and a large amount of power can be obtained instantaneously from the power layer.

IN THE CLAIMS:

Please cancel claims 1-8, 14-21, 27-31, 34-36, 39 and 47, without prejudice or disclaimer.

Please enter the following amended claims:

9 (Amended). A circuit board comprising a substrate and built thereon, a circuit comprised of a copper film,

wherein said copper film comprises an electroplated layer and has properties that (a) its crystallinity is such that the X-ray diffraction half-width of the (331) plane of copper is less than 0.3 deg. and (b) the variation in thickness ((maximum thickness-minimum thickness)/average thickness) of said copper film as measured over the whole surface of said substrate is not greater than 0.4.